L Number	Hits	Search Text	DB	Time stamp
-	280	((ball or solder) near5 completely near5 (remove or removing or removed or etch or etched or etching or clean or cleaning or cleaned))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 14:58
-	18	((ball or solder) near completely near (remove or removing or removed or etch or etched or etching or clean or cleaning or cleaned))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 14:54
-	49	(((ball or solder) near5 completely near5 (remove or removing or removed or etch or etched or etching or clean or cleaning or cleaned))) and (etch or etching or etched)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 14:55
-	26	((((ball or solder) near5 completely near5 (remove or removing or removed or etch or etched or etching or clean or cleaning or cleaned))) and (etch or etching or etched)) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 14:55
-	8	((resin or coat or coating or epoxy) near5 completely near5 (remove or removing or removed or etch or etched or etching or clean or cleaning or cleaned) near5 (solder or ball or bump))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 15:02
-	7	((resin or coat or coating or epoxy) near10 completely near10 (remove or removing or removed or etch or etched or etching or clean or cleaning or cleaned) near10 (solder or ball or bump)) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 15:19
-	11	((resin or coat or coating or epoxy) near20 completely near20 (remove or removing or removed or etch or etched or etching or clean or cleaning or cleaned) near20 (solder or ball or bump)) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 15:14
-	0	((resin or epoxy) near5 (ball or bump) near5 completely near5 (remove or removing or removed or etch or etching or etched or clean or cleaning or cleaned)) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 15:27
-	3	((resin or epoxy) near10 (ball or bump) near10 completely near10 (remove or removing or removed or etch or etching or etched or clean or cleaning or cleaned)) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 15:30
-	6	((resin or epoxy) near30 (ball or bump) near30 (completely or fully) near30 (remove or removing or removed or etch or etching or etched or clean or cleaning or cleaned)) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 15:34

-	7515	(resin or epoxy) near2 (ball or solder or bump)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 15:36
-	20	((resin or epoxy) near2 (ball or solder or bump)) near5 (completely or fully)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 15:38
-	4	((resin or epoxy) near2 (ball or solder or bump)) near5 (completely or fully) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 15:39
-	7	((resin or epoxy) near2 (ball or solder or bump)) near10 (completely or fully) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 15:40
-	39	((resin or epoxy) near5 (ball or solder or bump)) near20 (completely or fully) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 15:50
-	330	(resin or epoxy) near5 (ball or solder) near5 (remove or removed or removing or etch or etching or etched or clean or cleaned or cleaning)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 15:52
-	3	((resin or epoxy) near (ball or solder) near (remove or removed or removing or etch or etching or etched or clean or cleaned or cleaning)) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 15:54
-	109	((resin or epoxy) near5 (ball or bump) near5 (remove or removed or removing or etch or etching or etched or clean or cleaned or cleaning)) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 15:56
-	22	((resin or epoxy) near2 (ball or bump) near2 (remove or removed or removing or etch or etching or etched or clean or cleaned or cleaning)) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 16:02
-	4	(((resin or epoxy) near5 (ball or bump) near5 (remove or removed or removing or etch or etching or etched or clean or cleaned or cleaning)) near20 (completely or fully)) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 15:59

-		5	(((resin or epoxy) near5 (ball or bump) near5 (remove or removed or removing or etch or etching or etched or clean or cleaned or cleaning)) same (completely or fully)) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 16:02
-		6	(((resin or epoxy) near10 (ball or bump) near10 (remove or removed or removing or etch or etching or etched or clean or cleaned or cleaning)) same (completely or fully)) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 16:04
-		89	((resin or epoxy) near (completely or fully) near (remove or removing or removed or etch or etched or etching or clean or cleaning or cleaned))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 16:08
-		2	(((resin or epoxy) near (completely or fully) near (remove or removing or removed or etch or etched or etching or clean or cleaning or cleaned))) and (bump or ball) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 16:08
-		1994	((resin or epoxy) near10 (completely or fully) near10 (remove or removing or removed or etch or etched or etching or clean or cleaning or cleaned))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 16:08
-		60	(((resin or epoxy) near10 (completely or fully) near10 (remove or removing or removed or etch or etched or etching or clean or cleaning or cleaned))) and (bump or ball) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 16:09
-		35	((((resin or epoxy) near10 (completely or fully) near10 (remove or removing or removed or etch or etched or etching or clean or cleaning or cleaned))) and (bump or ball) and semiconductor) and ((bump or ball) near10 (epoxy or resin))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 16:09
-		4500	(resin near (coat or coating or coated)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 19:09
-		1340	(resin near (coat or coating or coated)).clm. and (resin near (coat or coating or coated)).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 19:09
-		51	(resin near (coat or coating or coated)).clm. and (resin near (coat or coating or coated)).ab. and (board or pcb).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 19:09

-		45	(resin near (coat or coating or coated)).clm. and (resin near (coat or coating or coated)).ab. and (board or pcb).ab. and (board or pcb).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 19:09
-		5	(resin near (coat or coating or coated)).clm. and (resin near (coat or coating or coated)).ab. and (board or pcb).ab. and (board or pcb).clm. and (bump or ball).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 19:10
-		5	((ball or bump) near resin near (coat or coating or coated)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 19:19
-		4500	(resin near (coat or coating or coated)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 19:33
-		5	((bump or ball) near resin near (coat or coating or coated)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 19:33
-		10	((bump or ball) near2 resin near2 (coat or coating or coated)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 19:34
-		45	((bump or ball) near5 resin near5 (coat or coating or coated)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 19:35
-		38	((bump or ball) near5 resin near5 (coat or coating or coated)) and adhesive and ((metal or gold or silver) near (bump or ball))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 19:35
-		20	((bump or ball) near5 resin near5 (coat or coating or coated)) and adhesive and ((metal or gold or silver) near (bump or ball)) and ((metal or gold or silver) near (layer or foil or film))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 19:37
-		15	((bump or ball) near10 resin near10 (coat or coating or coated)) and adhesive and ((metal or gold or silver) near (bump or ball)) and ((metal or gold or silver) near (layer or foil or film)) and (board or pcb)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 19:37

		11	bump.clm. and anam	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 19:39
-		129	((bump or ball) near2 (coat or coating or coated)).clm. and ((metal or gold or silver) near2 (ball or bump))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 19:40
-		62	((bump or ball) near2 (coat or coating or coated)).clm. and ((metal or gold or silver) near2 (ball or bump)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 19:40
-		19	((bump or ball) near2 (coat or coating or coated)).clm. and ((metal or gold or silver) near2 (ball or bump)).clm. and ((metal or gold or silver) near2 (layer or film or foil)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 19:40
-		4	((bump or ball) near2 (coat or coating or coated)).clm. and ((metal or gold or silver) near2 (ball or bump)).clm. and ((metal or gold or silver) near2 (layer or film or foil)).clm. and (board or pcb).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 19:40
-		43	((bump or ball) near2 (coat or coating or coated)).clm. and ((metal or gold or silver) near2 (ball or bump)) and ((metal or gold or silver) near2 (layer or film or foil)) and (board or pcb)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 19:41
-		252	((bump or ball) near2 (coat or coating or coated)) and ((metal or gold or silver) near2 (ball or bump)) and ((metal or gold or silver) near2 (layer or film or foil)) and (board or pcb)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 19:41
-		53	((bump or ball) near2 (coat or coating or coated)) and ((metal or gold or silver) near2 (ball or bump)) and ((metal or gold or silver) near2 (layer or film or foil)) and (board or pcb) and resin.clm. and (bump or ball).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 19:41
-		38	((bump or ball) near2 (coat or coating or coated)) and ((metal or gold or silver) near2 (ball or bump)) and ((metal or gold or silver) near2 (layer or film or foil)) and (board or pcb) and resin.clm. and (bump or ball).clm. and (bump or ball).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 19:41
-		12	((bump or ball) near2 (coat or coating or coated)) and ((metal or gold or silver) near2 (ball or bump)) and ((metal or gold or silver) near2 (layer or film or foil)) and (board or pcb) and resin.clm. and (bump or ball).clm. and (bump or ball).ab. and resin.ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 19:42

-	38	((bump or ball) near2 (coat or coating or coated)) and ((metal or gold or silver) near2 (ball or bump)) and ((metal or gold or silver) near2 (layer or film or foil)) and (board or pcb) and resin.clm. and (bump or ball).clm. and (bump or ball).ab. and (board or pcb)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 19:43
-	26	((bump or ball) near2 (coat or coating or coated)) and ((metal or gold or silver) near2 (ball or bump)) and ((metal or gold or silver) near2 (layer or film or foil)) and (board or pcb) and resin.clm. and (bump or ball).clm. and (bump or ball).ab. and (board or pcb) and adhesive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 19:44
-	35	(US-6294316-$ or US-5908317-$ or US-6259159-$ or US-6255740-$ or US-6054171-$ or US-5641113-$ or US-6165885-$ or US-6181569-$ or US-5998861-$ or US-5956605-$ or US-5891795-$ or US-5600180-$ or US-5591941-$ or US-6245490-$ or US-6063647-$ or US-5426850-$ or US-5873161-$ or US-6352881-$ or US-5808360-$ or US-6222279-$ or US-6043564-$ or US-6008071-$ or US-5866475-$ or US-6448633-$ or US-6475896-$ or US-6255737-$).did. or (US-6212768-$ or US-6428393-$ or US-6643923-$ or US-6091141-$).did. or (US-20010050434-$ or US-20010003656-$ or US-20020022301-$).did. or (JP-2000216522-$).did. or (US-5075965-$).did.	USPAT; US-PGPUB; JPO; DERWENT	2004/02/20 19:45
-	1	(US-3512051-$).did.	USOCR	2004/02/20 19:45
-	4500	(resin near (coat or coating or coated)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 19:51
-	9	((bump or ball) near2 (resin near (coat or coating or coated))).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 19:51
-	5	((bump or ball) near2 (resin near (coat or coating or coated))).clm. and adhesive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 19:52

.	12	((bump or ball) near5 (resin near (coat or coating or coated))).clm. and adhesive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 19:52
.	73	((bump or ball) near5 (resin near (coat or coating or coated))) and adhesive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 19:52
.	21	((bump or ball) near5 (resin near (coat or coating or coated))) and adhesive and ((metal or gold or silver) near2 (bump or ball))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/20 19:53